

Docket No.: JCLA31951

Form 1595 (Rev. 09/04)

RECORDATION FORM COVER SHEET

U.S. Department of Commerce
Patent and Trademark OfficePATENTS ONLY

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of conveying party(ies):

Names(s)

Date of Execution

Lin, Chun-Hsien,

September 18, 2009

2. Name/address of receiving Party(ies):

United Microelectronics Corp.No. 3, Li-Hsin Rd. II,
Science-Based Industrial Park,
Hsinchu, Taiwan, R.O.C.3. Nature of conveyance: ☒ Assignment☐ Merger ☐ Security Agreement ☐ Other☐ Change of Name ☐ Reassignment

Add'l name(s)/address(es) of receiving parties

Attached? ☐ Yes ☒ No

4. Application number(s) or patent number(s):

A. Patent Application No. (s)

12/572,498

Additional numbers attached?

B. Patent No. (s)

☐ Yes ☒ No

5. Name and address of party to whom Correspondence concerning document should be mailed:

J. C. Patents
4, Venture Suite 250
Irvine, CA. 92618
Tel: (949) 660-0761
Fax: (949) 660-0809
E-mail: jcpi@msn.com

6. Total No. of applications and patents involved:

ONE(1)

7. Total fee (37 CFR §3.41): **\$40.00**☐ Authorized to be charge by credit card☒ Authorized to be charge to deposit account☐ Enclosed☐ None required (government interest not affecting title)

8. Payment Information

a. Credit Card Last Numbers _____

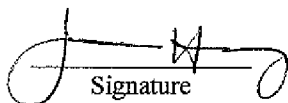
Expiration Date _____

b. Deposit Account Number 50-0710Authorized User Name Jiawei Huang

Atty Docket No.: JCLA31951

9. Statement and Signature:

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Jiawei HuangName of Person Signing
Registration No. 43,330
Signature10-2-2009
DateTotal number of pages
including cover sheet,
attachments, and
documents: 3

CH \$40.00 500710 12572498

UMCD-2009-0030
31951-US-PA

ASSIGNMENT

WHEREAS,

1. Chun-Hsien Lin

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **SEMICONDUCTOR DEVICE AND METHOD FOR FABRICATING THE SAME**

☐ Filed: Serial No.

☒ Executed concurrently with the execution of this instrument

WHEREAS, United Microelectronics Corp.
of No. 3, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

UMCD-2009-0030
31951-US-PA

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: Chun-Hsien Lin Date: 2009 Sep 18

Sole or First Joint Inventor: Chun-Hsien Lin